1. Name of conveying party(ies):

Benson (NMN) Chan, Frank D. Egitto, Voya R. Markovich

Additional names of conveying party(ies) attached? 
____ Yes ___ No

2. Name and address of receiving party(ies):

Name: Endicott Interconnect Technologies, Inc.

Street Address: 1701 North Street
City: Endicott
State: New York Zip: 13760

Additional name(s) & address(es) attached? ___ Yes ___ No

3. Nature of Conveyance 

____ Assignment ______ Merger
____ Security Agreement ______ Change of Name
____ Other _______________________

Execution Date: 11/16/06

4. Application number(s) or patent number(s):

Title: INTERPOSER AND TEST ASSEMBLY FOR TESTING ELECTRONIC DEVICES

If this document is being filed together with a new application, the execution date of the application is 11/16/06

A. Patent Application No(s). 
B. Patent No(s). ______

Additional numbers attached? ___ Yes ___ No

ATTORNEY DOCKET NUMBER EI-2-06-010

5. Name and address of party to whom correspondence concerning document should be mailed:

Hinman, Howard & Kattell, LLP
700 Security Mutual Building
80 Exchange Street
Binghamton, New York 13901

Att: Lawrence R. Fraley

12/07/2006 DBYRNE 00000079 11607973 01 FC:8021 40.00 OP

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41):

$$40.00$$

___ Enclosed

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8. Statement and signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Lawrence R. Fraley
Name of Person Signing

Signature

12/01/06 Date

Registration # 26,885 Tel: 561-575-3608 Total number of pages comprising cover sheet: 2
ASSIGNMENT

Whereas, We

(1) Benson (NMN) Chan
   County of Broome
   City of Vestal
   And State of New York

(2) Frank D. Egitto
   County of Broome
   City of Binghamton
   And State of New York

(3) Voya R. Markovich
   County of Broome
   City of Endwell
   And State of New York

have invented certain improvements in INTERPOSER AND ELECTRICAL ASSEMBLY
FOR TESTING ELECTRONIC DEVICES
and have executed, respectively, a United States patent application therefor on

(1) 11/16/06, (2) 11/16/06, (3) 11/16/06.

And whereas, ENDICOTT INTERCONNECT TECHNOLOGIES, INC., a corporation
of New York, having a place of business at Endicott, New York 13760, (hereinafter called EI),
desires to acquire the entire right, title and interest in the said application and invention, and to
any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged,
we the above named hereby sell, assign, and transfer to EI, its successors and assigns, the entire
right, title and interest in the said application and invention therein disclosed for protection in
the United States and foreign countries, and all rights of priority resulting from the filing of
said United States application, and we request the Commissioner of Patents to issue any Letters
Patent granted upon the invention set forth in said application to EI, its successors and assigns;
and we hereby agree that EI may apply for foreign Letters Patent on said invention and we will
execute all papers necessary in connection with the United States and foreign applications
when called upon to do so by EI.

Signed:

at Endicott, New York, this 16 day of November, 2006.

Benson (NMN) Chan

at Endicott, New York, this 16 day of November, 2006.

Frank D. Egitto

at Endicott, New York, this 16 day of November, 2006.

Voya R. Markovich